



High end Production in Leoben

### Unique market position

AT&S is the European market leader and one of the globally leading manufacturers of high-value printed circuit boards. AT&S industrialises leading-edge technologies for its core business segments Mobile Devices (Smartphones, Tablets, Ultrabooks, Consumer Electronics), Automotive (high-end applications like advanced driver assistance systems – lane change assistant, navigation – or safety features, gearbox, etc.), Industrial (machine to machine communication, power solutions,..), Medical (diagnosis like MRT or therapy applications like hearing aids, pacemakers, etc.) and Advanced Packaging (Chip embedding).

### Global Presence / Customer and supply chain proximity

AT&S has a global presence, with production facilities in Austria (Leoben and Fehring) and plants in India (Nanjangud), China (Shanghai, Chongqing under construction) and Korea (Ansan, near Seoul). The company currently employs about 8,600 people.

### Clear focus on high-end connecting solutions and applications

Depending on technological requirements, AT&S offers an extensive technological range of printed circuit boards specially tailored to customers' needs: from double-sided plated-through, multi-layer, HDI

(high density interconnection, laser-drilled) or HDI Anylayer, IMS (insulated metallic substrate), flexible, rigid-flex and semi-flexible. Miniaturisation and modularisation are the key drivers in the electronic industry. Starting in 2016, AT&S will position itself in the high-end market at the new site in Chongqing (China) with two new leading-edge technologies:

IC substrates for high-performing computing applications and substrate-like printed circuit boards – the basis for SiP (System-in-Package) technology.

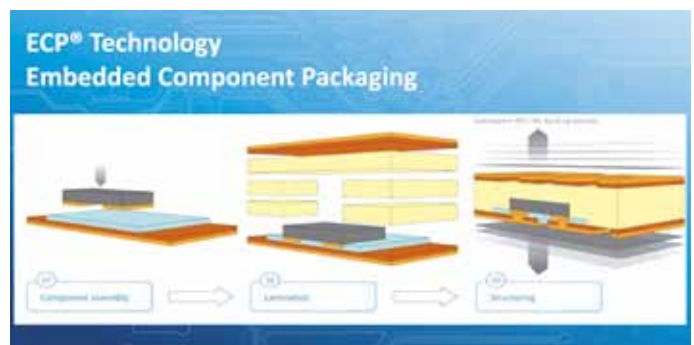
### Advanced packaging – important part of the future growth for AT&S

AT&S is the leading provider for Embedded Component Packaging Solutions. Its patented ECP® technology enables further miniaturisation while improving performance.

### Power a further focus for embedding technology

Together with the EmPower consortium AT&S announced the stage of industrialisation for embedded power packages for Industrial and Automotive applications. This solution provides a significant increase in efficiency and performance and miniaturisation levels up to 50% for power modules compared to existing packaging solutions. New plating equipment for wafer level plating has been developed in order to realise double sided copper plated power dies. This enables a new supply chain for embedded power devices and new packaging solutions for applications in the power ranges from 50W to 50kW.

Further information for EmPower <http://catrene-empower.ats.net/>



Embedding technology for volume production



2 KW Power converter with embedded GaN semiconductors